

ON-BOARD TEST DATA

Date:		P/N:		S/N:		R/N:	
Test:		Test Plate : ON-BOARD				Assy OK:	
ON-BOARD TEST REQUIREUEMENTS		ACTUAL READING		READING TIME		PASS	
SUPPLY PRESSURE		PSI				PASS	
RETURN PRESSURE		PSI				PASS	
Δ - P		PSI				PASS	
COMPRESSOR		Δ -P Setup : 220 ~ 260 PSI				N/A	
		Model:		of		N/A	
Diode Reading @ Room Temp		1st	K			PASS	
		2nd	K				
START TIME				N/A		N/A	
Minute to 17K/ Spec=		Mins=				PASS	
Minute to Bottom Out		Mins=				PASS	
Bottom Out Reading After 14K, Spec = < 50K 1st stage and \leq 10.9K 2nd stage		1st:	K	2nd:	K		
1st Stage Temp Control Test Spec =65k \pm 2K		#1 15 Mins	1st K ; 2nd K	N/A		PASS	
		#2 15 Mins	1st K ; 2nd K				
2nd Stage Heater Test		Warm Up:				PASS	
RESET FACTORY REGEN PARAMETER Extended purge = 60 mins, Repurge = 5 mins, Rough pressure = 50 Micron, ROR limit = 10 u/min, ROR cycles = 20, 1st stage temp = 0K, 2nd stage temp = 0K		Leak Rate of Helium side : SPEC: 5×10^{-6} mbar.l / sec Leak Rate of Vacuum side: SPEC: 5×10^{-9} mbar.l / sec				PASS	
PASS							
Acceptance Criteria							
Cryopump		(Mins. Max.) Cooldown	(Mins. Max.) 2nd Stage Warm Up	Bottom Out (K) 1st Stage / 2nd Stage		1st Stage Temp. Control (K)	
	ON-BOARD 4/4F	62	15	<50 / \leq 10.9		65 \pm 2	
	ON-BOARD 6	75	15	<50 / \leq 10.9		65 \pm 2	
	ON-BOARD 8	100	18	<50 / \leq 10.9		65 \pm 2	
V	ON-BOARD 8F/8FE	105	20	<50 / \leq 10.9		65 \pm 2	
	ON-BOARD 250F High Capacity	150	20	<50 / \leq 10.9		65 \pm 2	
	ON-BOARD 10/10F	95	22	<50 / \leq 10.9		65 \pm 2	
	ON-BOARD 400	150	25	<50 / \leq 10.9		65 \pm 2	